



Product Change Notification

Change Notification #: 117467 - 00
Change Title: Intel® RAID Maintenance Free Backup
AXXRMFBU4,
PCN 117467-00, Product Design,
Order Code,
Updates made to firmware, connectors,
cable and mounting bracket
Date of Publication: March 5, 2020

Key Characteristics of the Change:

Product Design, Order Code

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	March 5, 2020
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel has implementing the following change on the Intel® RAID Maintenance Free Backup AXXRMFBU4:

1. Update microcontroller firmware.
2. Update Supercap version to v15.
3. Change connector type on PCB.
4. Change cables to match connector type on PCB.
5. Change the retention bracket to improve attachment, now it includes a separate locking tab.

See figures 1 and 2 on the next page to better understand the changes on the connectors, cable and mounting bracket.

Figure1. Connector and cable change

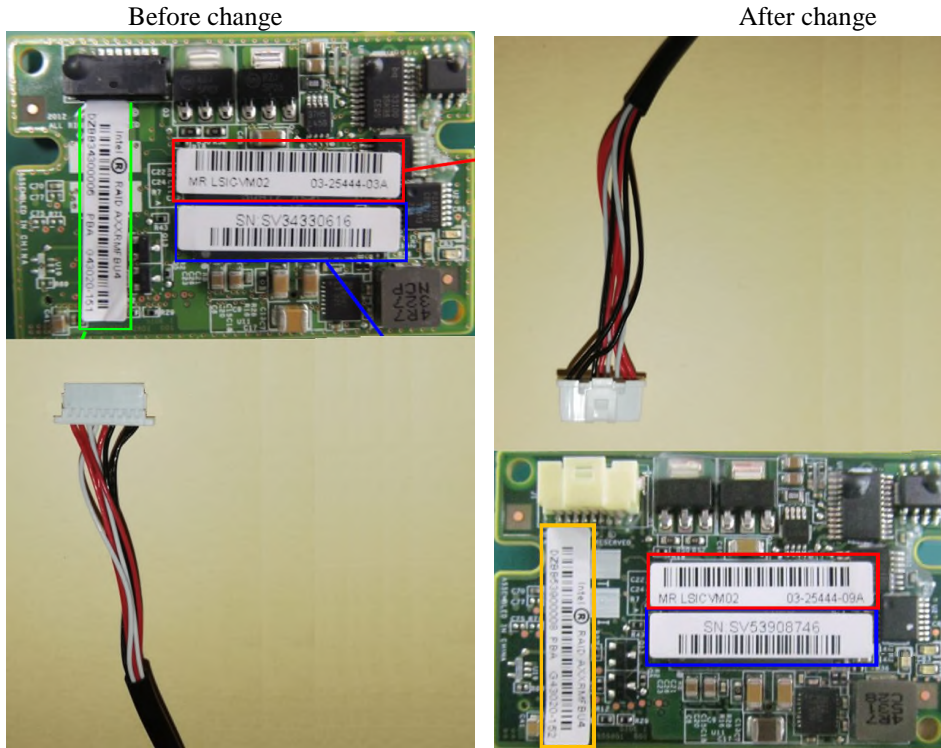
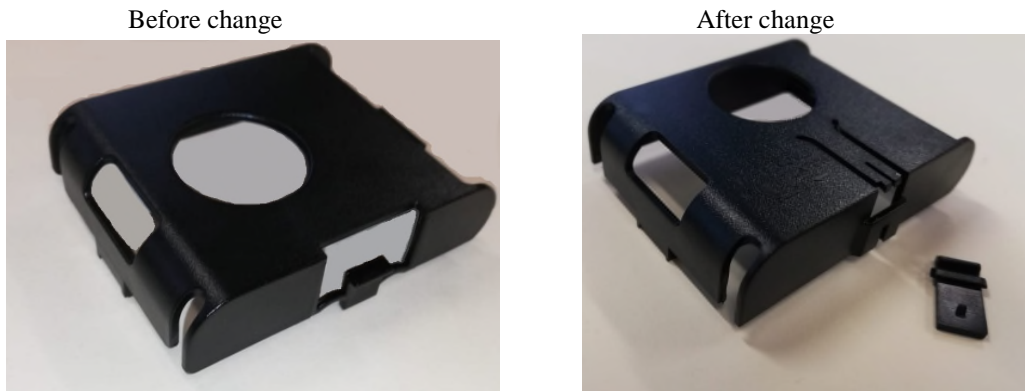


Figure2. Retention bracket change



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change.

Products Affected / Intel Ordering Codes:

Product Code	Pre Change MM#	Pre Change TA	Post Change MM#	Post Change TA
AXXRMFBU4	929734	H17988-001	937318	H17988-002

PCN Revision History:

Date of Revision:

March 5, 2020

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

117467 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apagccb@intel.com

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